

Dual N-Channel 20-V (D-S) MOSFET
GENERAL DESCRIPTION

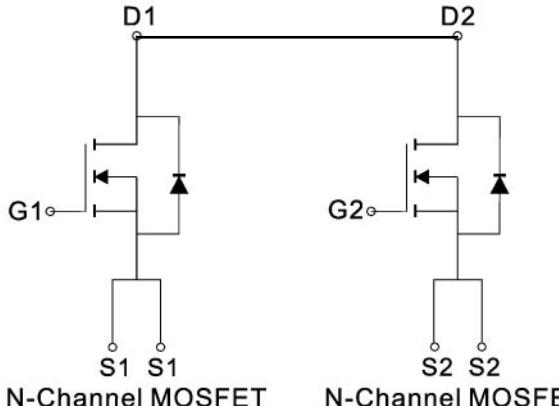
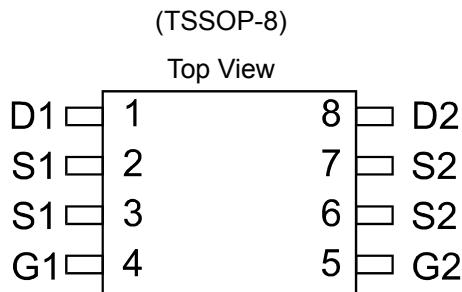
The ME6970 Dual N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits where high-side switching, and low in-line power loss are needed in a very small outline surface mount package.

FEATURES

- $R_{DS(ON)} \leq 21\text{m}\Omega @ V_{GS}=10\text{V}$
- $R_{DS(ON)} \leq 24\text{m}\Omega @ V_{GS}=4.5\text{V}$
- $R_{DS(ON)} \leq 32\text{m}\Omega @ V_{GS}=2.5\text{V}$
- $R_{DS(ON)} \leq 50\text{m}\Omega @ V_{GS}=1.8\text{V}$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability

APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- Load Switch

PIN CONFIGURATION


Ordering Information: ME6970 (Pb-free)

ME6970-G (Green product-Halogen free)

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ Unless Otherwise Noted)

Parameter		Symbol	Maximum Ratings	Unit
Drain-Source Voltage		V_{DS}	20	V
Gate-Source Voltage		V_{GS}	± 12	V
Continuous Drain Current	$T_A=25^\circ\text{C}$	I_D	6.1	A
	$T_A=70^\circ\text{C}$		4.9	
Pulsed Drain Current		I_{DM}	24.4	A
Maximum Power Dissipation	$T_A=25^\circ\text{C}$	P_D	1.3	W
	$T_A=70^\circ\text{C}$		0.8	
Operating Junction Temperature		T_J	-55 to 150	°C
Thermal Resistance-Junction to Ambient*		$R_{\theta JA}$	100	°C/W

* The device mounted on 1in² FR4 board with 2 oz copper



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Electrical Characteristics (TA = 25°C Unless Otherwise Specified)

Symbol	Parameter	Limit	Min	Typ	Max	Unit
STATIC						
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250 μA	20			V
V _{G(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250 μA	0.5		1	V
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} =±12V			±100	nA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =16V, V _{GS} =0V			1	μA
R _{D(ON)}	Drain-Source On-State Resistance ^a	V _{GS} =10V, I _D = 7A		16.5	21	mΩ
		V _{GS} =4.5V, I _D = 6.6A		19	24	
		V _{GS} =2.5V, I _D = 5.5A		23	32	
		V _{GS} =1.8V, I _D = 2A		30	50	
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V		0.7	1	V
DYNAMIC						
Q _g	Total Gate Charge	V _{DS} =10V, V _{GS} =4.5V, I _D =7A		9.5		nC
Q _{gs}	Gate-Source Charge			3.9		
Q _{gd}	Gate-Drain Charge			2.8		
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, f=1MHz		690		pF
C _{oss}	Output Capacitance			99		
C _{rss}	Reverse Transfer Capacitance			31.3		
R _g	Gate resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz		1.5		Ω
t _{d(on)}	Turn-On Delay Time	V _{DD} =10V, R _L =3Ω V _{GEN} =5V, R _G =3Ω		13.5		ns
t _r	Turn-On Rise Time			33.6		
t _{d(off)}	Turn-Off Delay Time			39.3		
t _f	Turn-Off Fall Time			4.8		

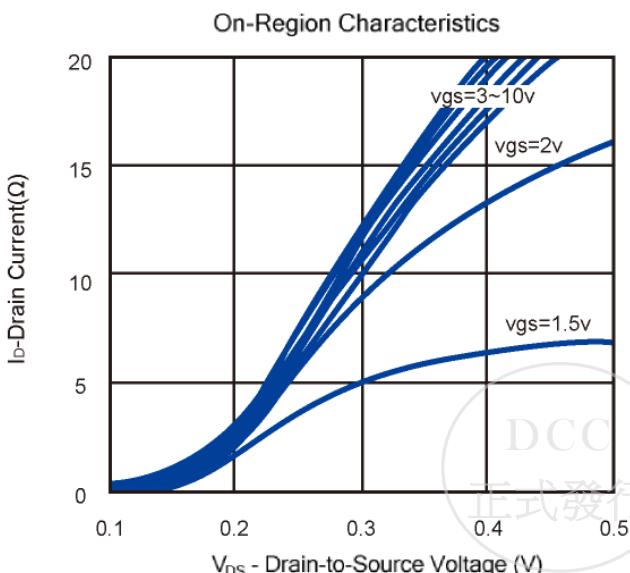
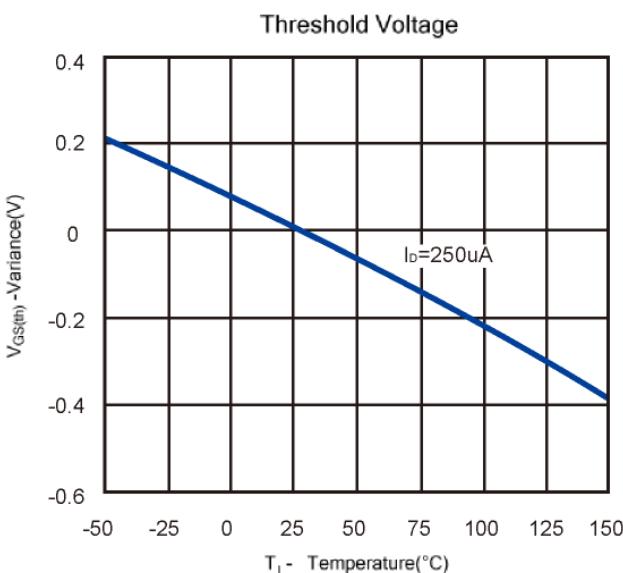
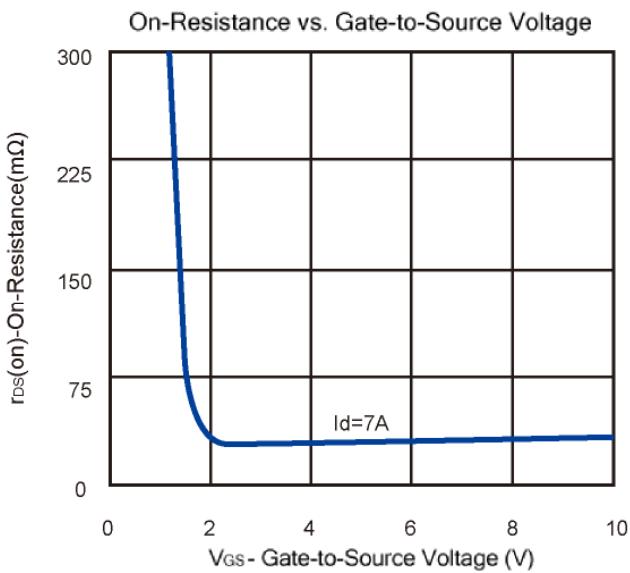
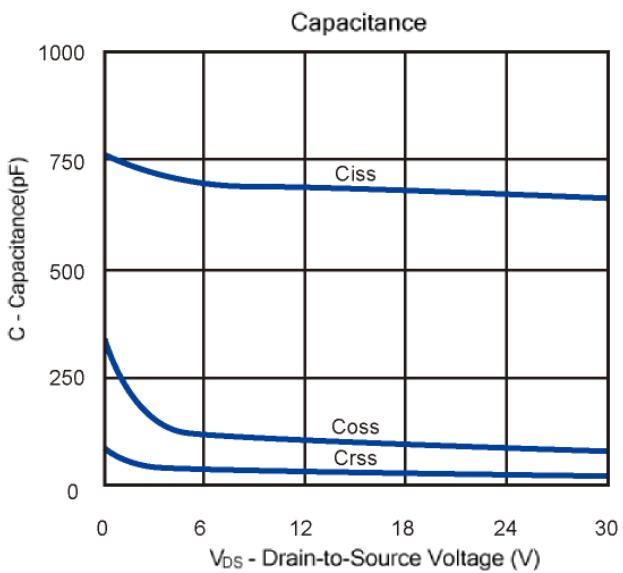
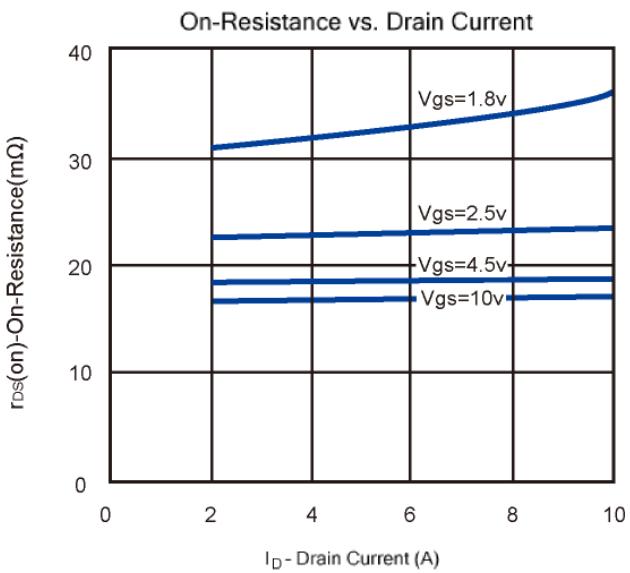
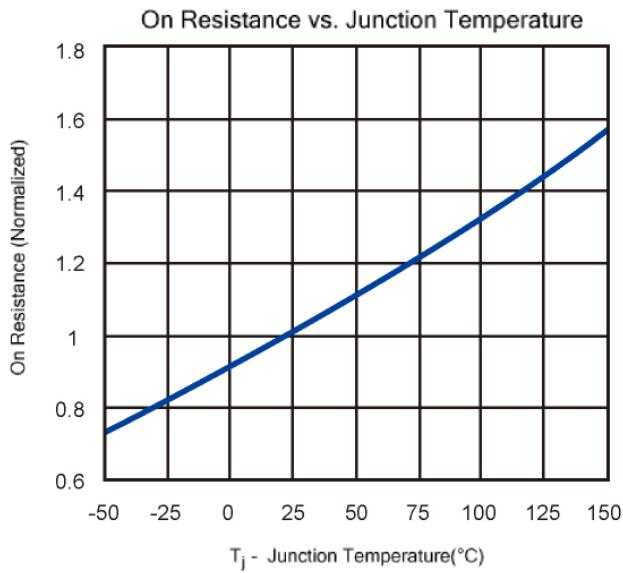
Notes: a. pulse test: pulse width ≤ 300us, duty cycle ≤ 2%, Guaranteed by design, not subject to production testing.

b. Matsuki Electric/ Force mos reserves the right to improve product design, functions and reliability without notice.



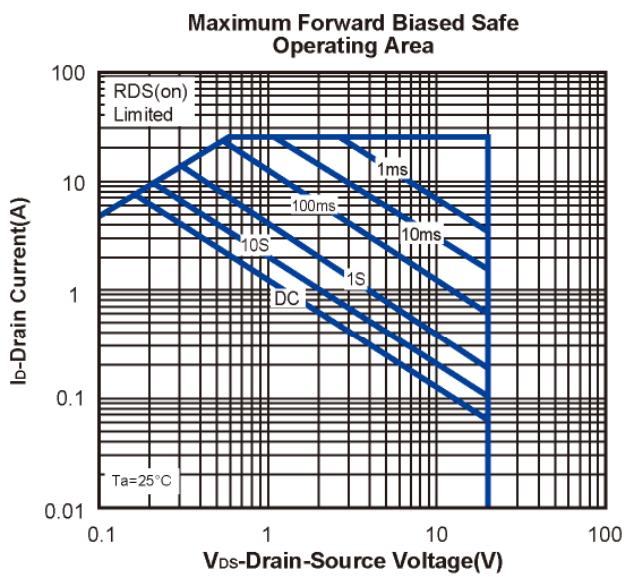
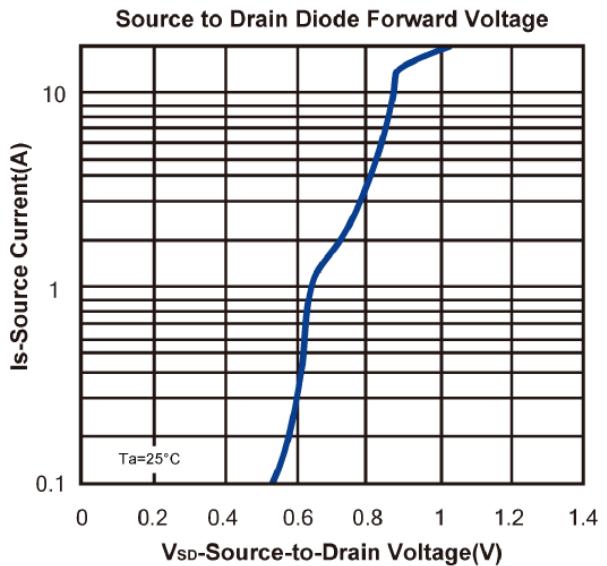
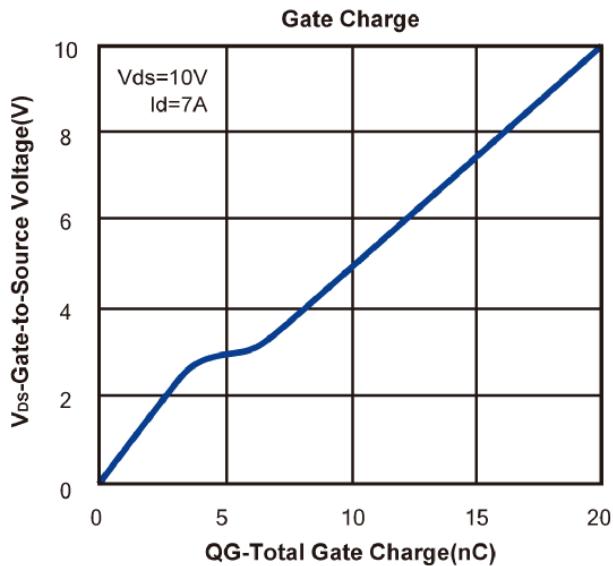
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Typical Characteristics ($T_J = 25^\circ\text{C}$ Noted)

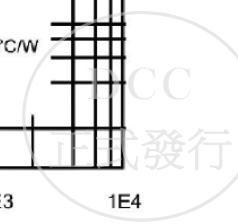
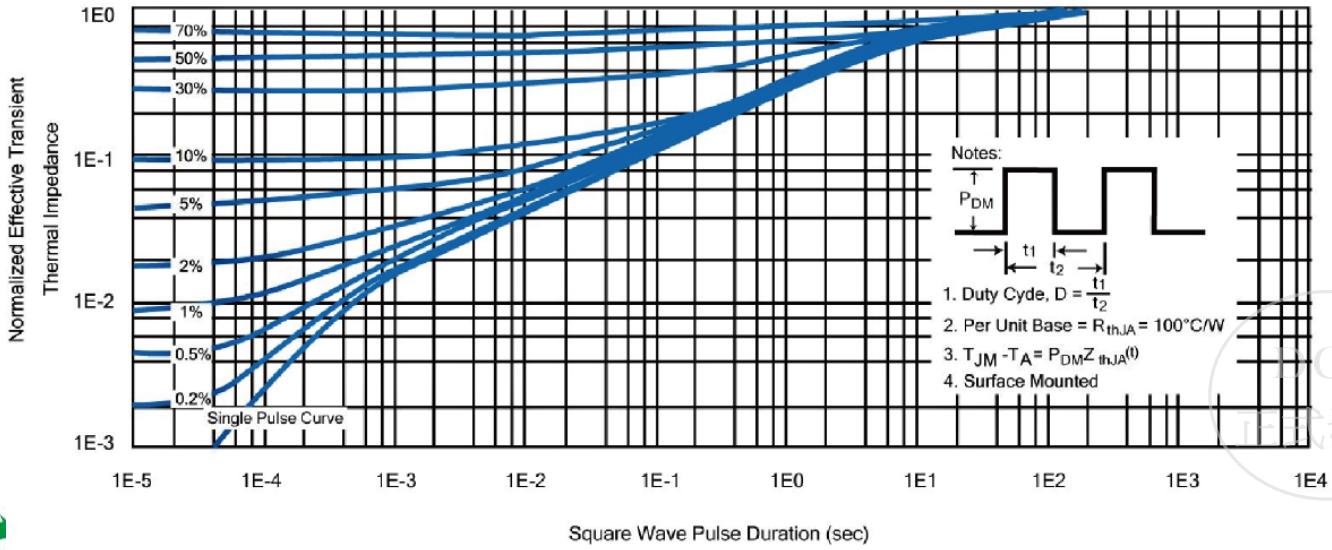


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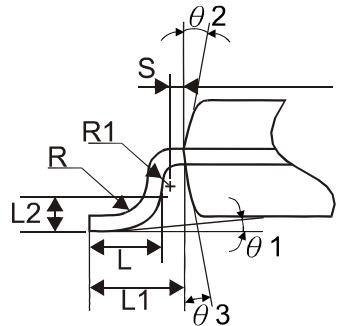
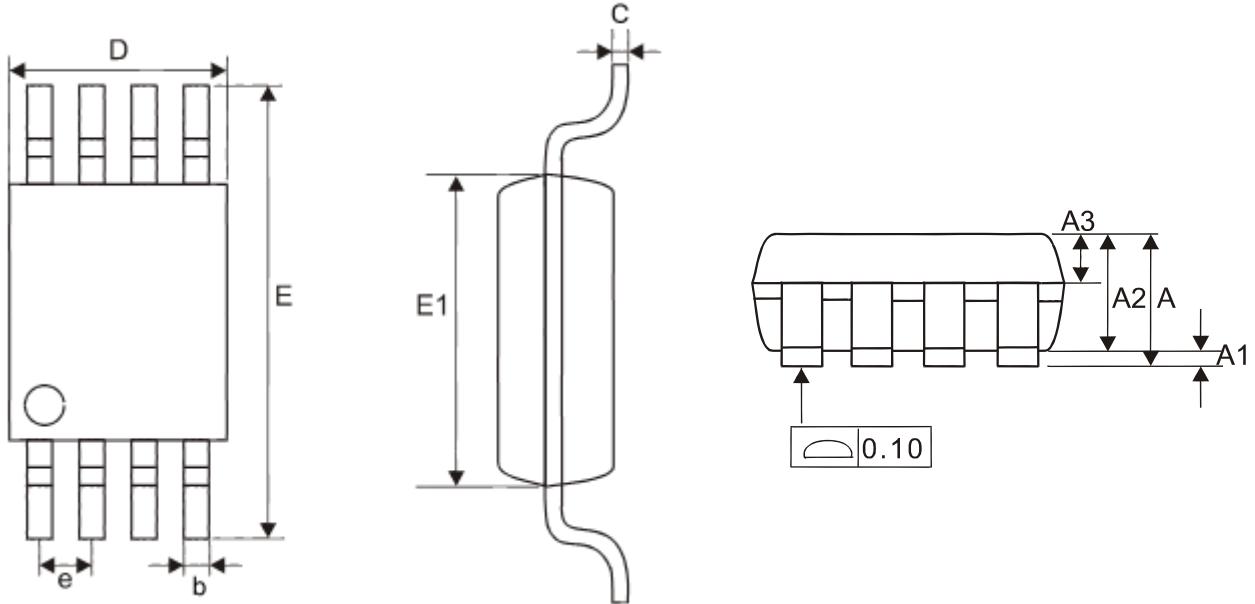
Typical Characteristics (T_J = 25°C Noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



TSSOP-8 Package



SYMBOL	MILLIMETERS (mm)	
	MIN	MAX
A	-	1.20
A1	0.05	0.15
A2	0.90	1.05
A3	0.34	0.54
b	0.19	0.30
c	0.09	0.20
D	2.90	3.10
E	6.20	6.60
E1	4.30	4.50
e	0.65BSC	
L	0.45	0.75
L1	1.00REF	
L2	0.25BSC	
R	0.09	-

